

 <small>ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®</small>		<b>Material Composition Declaration</b> <small>© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.</small>		<small>This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.</small> <b>Adobe Reader version 7.0.5 is required to complete this declaration.</b>					
<b>1752-2 1.1</b>		IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>			<b>Form Type *</b> Distribute		<b>Declaration Class *</b> Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat		
<b>Supplier Information</b>									
<b>Company Name *</b> Cypress Semiconductor Corp		Company Unique ID CYPRESS		Unique ID Authority		<b>Response Date *</b> 2009-12-08		Response Document ID	
<b>Contact Name *</b> Richard Oshiro		Title - Contact QA Engrg Director		<b>Phone - Contact *</b> 408/943-2102		<b>Email - Contact *</b> rgo@cypress.com		Duplicate Contact -> Authorized Representative	
<b>Authorized Representative *</b> Glorioso Lutrinia		Title - Representative EH & S Manager Sr.		<b>Phone - Representative *</b> 632 8128161		<b>Email - Representative *</b> lge@cypress.com		Supplier Comments or URL for Additional Information	
Requester Item Number		Mfr Item Number		Mfr Item Name		Effective Date		Version	
		48L-TSOP I		48L-TSOP I		2009-12-08			
Alternate Recommendation						Alternate Item Comments		Package QTP 071906	
<b>Manufacturing Process Information</b>									
Terminal Plating / Grid Array Material <b>Nickel/Palladium/Gold (Ni/Pd/Au)</b>		Terminal Base Alloy <b>CU Alloy</b>		J-STD-020 MSL Rating <b>3</b>		Peak Process Body Temperature <b>260 C</b>		Max Time at Peak Temperature <b>20 seconds</b>	
								Number of Reflow Cycles <b>3</b>	
Comments									
<b>Compliant to RoHS requirements</b>									

RoHS Material Composition Declaration

Declaration Type \*Detailed

RoHS Directive 2002/95/EC

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.

RoHS Declaration \*1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \*Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem Name					Homogeneous Material	Weight	Unit of Measure			Level	Substance Category			Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
																			-	+	
+I	-I	Base material	+M	-M	Lead frame	118.94	mg	+C	-C	Supplier	Copper	+S	-S	Copper	7440-50-8		117.64	mg			217,09
								+C	-C	Supplier	Silicon	+S	-S	Silicon	7440-21-3		0.9	mg			1,661
								+C	-C	Supplier	Magnesium	+S	-S	Magnesium	7439-95-4		0.22	mg			401
								+C	-C	Supplier	Polyimide	+S	-S	Polyimide	Trade Secret		0.12	mg			214
								+C	-C	Supplier	NBR	+S	-S	NBR	9003-18-3		0.02	mg			36
								+C	-C	Supplier	Bismaleimide	+S	-S	Bismaleimide	79922-55-7		0.02	mg			36
								+C	-C	Supplier	Phenol resin	+S	-S	Phenol resin	28453-20-5		0.02	mg			31
								+I	-I	External Plating	+M	-M	Lead finish	5.19	mg	+C	-C	Supplier	Nickel	+S	-S
								+C	-C	Supplier	Palladium	+S	-S	Palladium	7440-05-3		0.1	mg			186
								+C	-C	Supplier	Gold	+S	-S	Gold	7440-57-5		0.02	mg			32
								+I	-I	Adhesive	+M	-M	Die attach	1.69	mg	+C	-C	Supplier	Acrylic resin	+S	-S
								+C	-C	Supplier	Polybutadiene deriva	+S	-S	Polybutadiene derivativ	Trade secret		0.09	mg			172
								+C	-C	Supplier	Butadiene copolyme	+S	-S	Butadiene copolymer	Trade secret		0.02	mg			31
								+C	-C	Supplier	Epoxy Resin	+S	-S	Epoxy Resin	Trade secret		0.03	mg			62
								+C	-C	Supplier	Acrylate	+S	-S	Acrylate	Trade secret		0.07	mg			125
								+C	-C	Supplier	Peroxide	+S	-S	Peroxide	Trade secret		0.01	mg			16
								+C	-C	Supplier	Additive	+S	-S	Additive	Trade secret		0.03	mg			47
								+C	-C	Supplier	Silver	+S	-S	Silver	7440-22-4		1.3	mg			2,401
+I	-I	Circuit	+M	-M	Die	19.88	mg	+C	-C	Supplier	Si	+S	-S	Si	7440-21-3		19.88	mg			36,682
+I	-I	Interconnect	+M	-M	Bonding wire	1.11	mg	+C	-C	Supplier	Au	+S	-S	Au	7440-57-5		1.11	mg			2,048
+I	-I	Encapsulation	+M	-M	Mold compound	395.1	mg	+C	-C	Supplier	Epoxy resin	+S	-S	Epoxy resin	Trade secret		17.78	mg			32,810
								+C	-C	Supplier	Phenol resin	+S	-S	Phenol resin	Trade secret		15.8	mg			29,164
								+C	-C	Supplier	Aromatic Phosphate	+S	-S	Aromatic Phosphate	Trade secret		5.14	mg			9,478

+C	-C	Supplier	Carbon black	+S	-S	Carbon black	1333-86-4		0.79	mg			1,458
+C	-C	Supplier	Silica	+S	-S	Silica	60676-86-0		355.59	mg			656,19